

## SOD-323 Plastic-Encapsulate ESD Protection Diodes

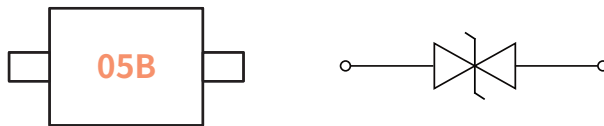
### Features

- Low leakage current
- SOD-323 surface mount package
- IEC 61000-4-2 (ESD Air):  $\pm 30\text{kV}$
- IEC 61000-4-2 (ESD Contact):  $\pm 30\text{kV}$
- IEC 61000-4-5 (Lightning 8/20 $\mu\text{s}$ ): 25A

### Applications

- LED Lighting Modules
- RS232/RS485
- CAN and LIN Bus
- Portable Instrumentation
- General Purpose I/O
- Automotive application

### Function Diagram



**Reverse Working Voltage**  
5V Max.  
**High capacitance**  
100pF(Max.)

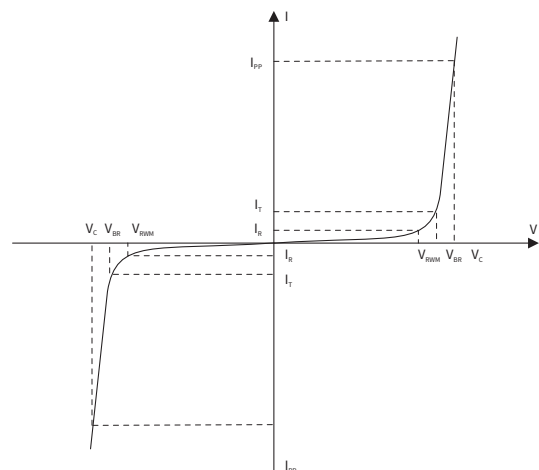


### Maximum Ratings (Ta=25°C Unless otherwise specified)

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
V <sub>ESD</sub>	Electrostatic Discharge Voltage	ESD per IEC 61000-4-2( Air )	$\pm 30$	KV
		ESD per IEC 61000-4-2( Contact)	$\pm 30$	KV
P <sub>PP</sub>	Peak Pulse Power	tp = 8/20 $\mu\text{s}$	400	W
I <sub>PP</sub>	Rated Peak Pulse Current	tp = 8/20 $\mu\text{s}$	25	A
T <sub>J</sub>	Operating JunctionTemperature Range	—	-55 to +125	°C
T <sub>STG</sub>	Operating JunctionTemperature Range	—	-55 to +150	°C

### Electrical Parameter

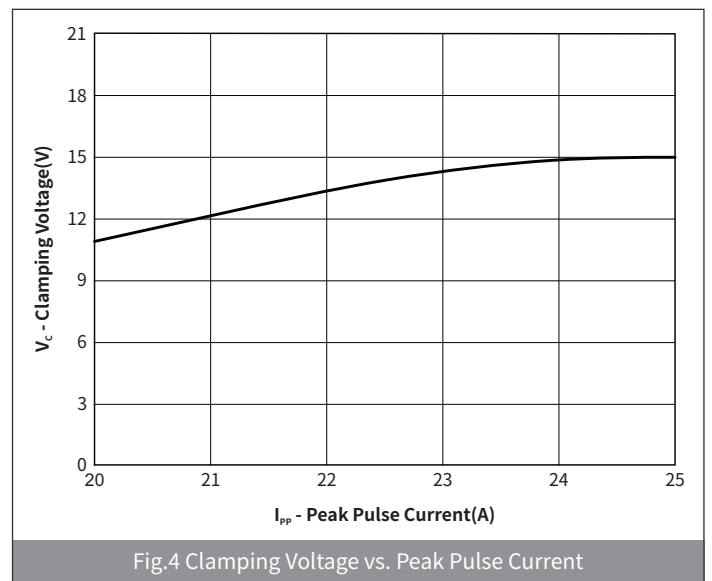
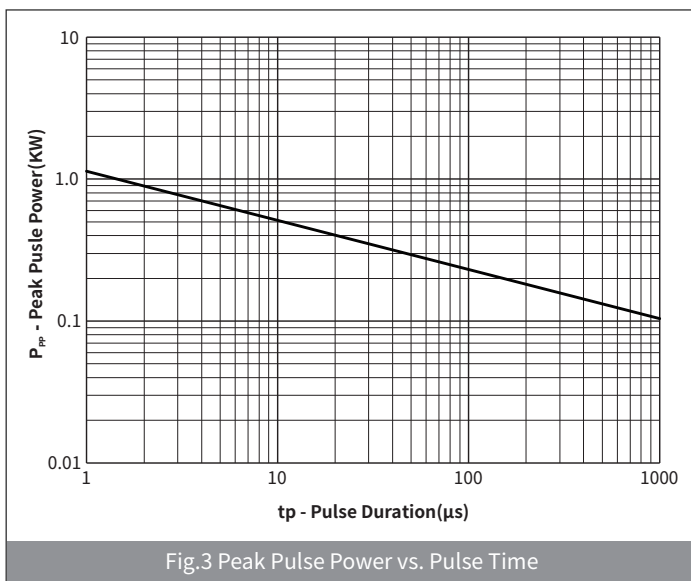
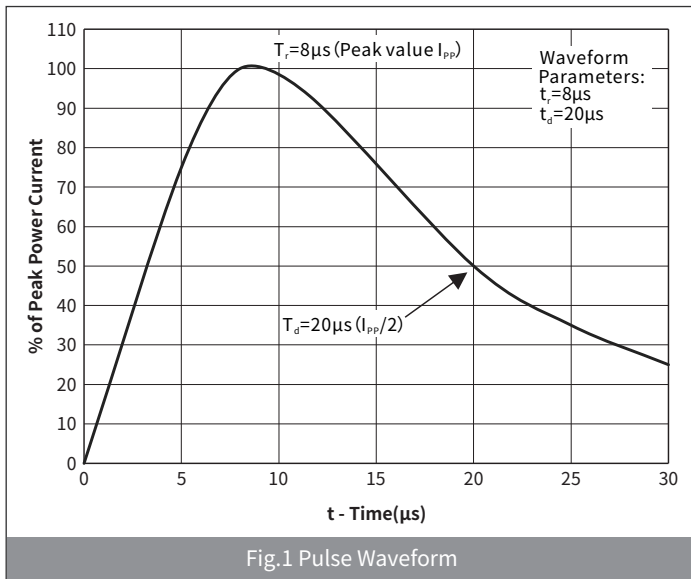
SYMBOL	PARAMETER
V <sub>C</sub>	Clamping Voltage @ I <sub>PP</sub>
V <sub>BR</sub>	Breakdown Voltage @ I <sub>T</sub>
I <sub>PP</sub>	Peak Pulse Current
I <sub>T</sub>	Test Current
I <sub>R</sub>	Reverse Leakage Current @ VRWM
V <sub>RWM</sub>	Peak Reverse Working Voltage
P <sub>PP</sub>	Peak Pulse Power Dissipation
C <sub>J</sub>	Junction Capacitance @ V <sub>R</sub> =0V,f=1MHz
I <sub>F</sub>	Forward Current
V <sub>F</sub>	Forward Voltage @I <sub>F</sub>



## Electrical Characteristics (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	CONDITION	Min	Typ	Max	UNIT
Peak Reverse Working Voltage	$V_{RWM}$	$T_a=25^\circ\text{C}$	—	—	5	V
Breakdown Voltage	$V_{BR}$	$I_R=1\text{mA}, T_a=25^\circ\text{C}$	6	—	9	V
Reverse Leakage Current	$I_R$	$V_R=5\text{V}, T_a=25^\circ\text{C}$	—	—	0.2	$\mu\text{A}$
Clamping Voltage	$V_C$	$I_{PP}=20\text{A}, t_p=8/20\mu\text{s}$	—	—	14	V
		$I_{PP}=25\text{A}, t_p=8/20\mu\text{s}$	—	—	16	
Junction Capacitance	$C_J$	$V_R=0\text{V}, f=1\text{MHz}$	—	—	100	pF

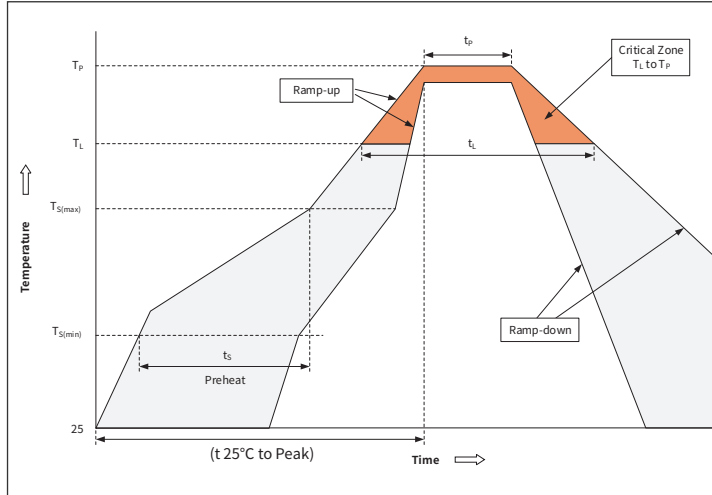
## Ratings And Characteristics Curves (Ta=25°C Unless otherwise specified)



## Ordering Information

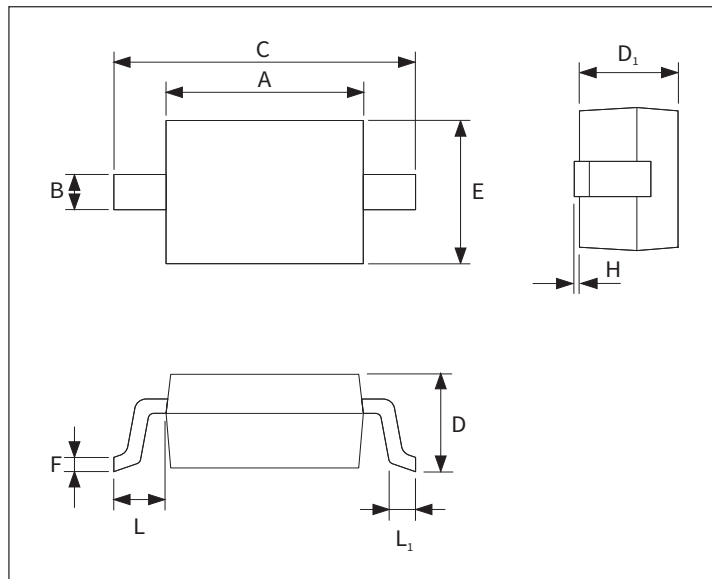
PREFERRED P/N	PACKAGE	SIZE(mm)	DELIVERY MODE	MPQ(PCS)
H5VHD3BC	SOD-323	2.55×1.30×0.95	7" REEL	3000

## Recommended Soldering Conditions



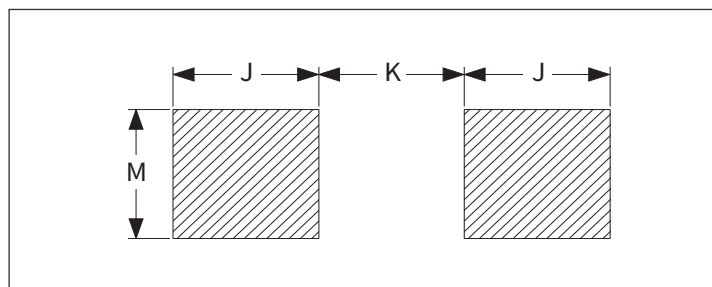
Profile Feature		Pb-Free Assembly
Pre-heat	Temperature Min ( $T_{S(min)}$ )	+150°C
	Temperature Max ( $T_{S(max)}$ )	+200°C
	Time (Min to Max) ( $t_s$ )	60-180 secs.
Average ramp up rate (Liquid us Temp ( $T_L$ ) to peak)		3°C/sec. Max
$T_{S(max)}$ to $T_L$ - Ramp-up Rate		3°C/sec. Max
Reflow	Temperature ( $T_L$ ) (Liquid us)	+217°C
	Temperature ( $t_L$ )	60-150 secs.
Peak Temp ( $T_P$ )		+260(+0/-5)°C
Time within 5°C of actual Peak Temp ( $t_p$ )		20-40secs
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp ( $T_P$ )		8 min. Max
Do not exceed		+260°C

## Package Outline Dimensions (SOD-323)



Symbol	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.60	1.80	0.063	0.071
B	0.25	0.40	0.010	0.016
C	2.30	2.80	0.091	0.110
D	0.80	1.10	0.031	0.043
D <sub>1</sub>	0.80	0.90	0.031	0.035
E	1.20	1.40	0.047	0.055
F	0.08	0.18	0.003	0.007
L	0.475REF		0.019REF	
L <sub>1</sub>	0.25	0.40	0.010	0.016
H	-	0.14	-	0.006

## Suggested Pad Layout



Symbol	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
J	0.80	-	0.031	-
K	-	1.40	-	0.055
M	0.80	-	0.031	-